

NTLJD3181PZ

Power MOSFET

–20 V, –4.0 A, Dual P–Channel, ESD,
2x2 mm WDFN Package

Features

- WDFN 2x2 mm Package with Exposed Drain Pads for Excellent Thermal Conduction
- Lowest $R_{DS(on)}$ Solution in 2x2 mm Package
- Footprint Same as SC–88 Package
- Low Profile (< 0.8 mm) for Easy Fit in Thin Environments
- ESD Protected
- This is a Pb–Free Device

Applications

- Optimized for Battery and Load Management Applications in Portable Equipment
- Li–Ion Battery Charging and Protection Circuits
- High Side Load Switch

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain–to–Source Voltage			V_{DSS}	–20	V
Gate–to–Source Voltage			V_{GS}	± 8.0	V
Continuous Drain Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	I_D	–3.2	A
		$T_A = 85^\circ\text{C}$		–2.3	
		$t \leq 5 \text{ s}$		–4.0	
Power Dissipation (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	P_D	1.5	W
		$T_A = 85^\circ\text{C}$		2.3	
		$t \leq 5 \text{ s}$		2.3	
Continuous Drain Current (Note 2)	Steady State	$T_A = 25^\circ\text{C}$	I_D	–2.2	A
		$T_A = 85^\circ\text{C}$		–1.6	
		$T_A = 25^\circ\text{C}$		0.71	
Power Dissipation (Note 2)	Steady State	$T_A = 25^\circ\text{C}$	P_D	0.71	W
Pulsed Drain Current		$t_p = 10 \mu\text{s}$		–16	
Operating Junction and Storage Temperature		T_J, T_{STG}		–55 to 150	
Source Current (Body Diode) (Note 2)			I_S	–1.0	A
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T_L	260	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

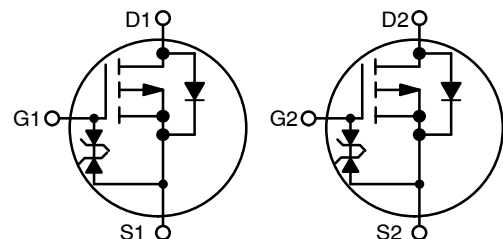
1. Surface Mounted on FR4 Board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).
2. Surface Mounted on FR4 Board using the minimum recommended pad size of 30 mm², 2 oz Cu.



ON Semiconductor®

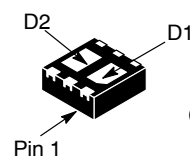
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$V_{(BR)DSS}$	$R_{DS(on)}$ MAX	I_D MAX (Note 1)
–20 V	100 m Ω @ –4.5 V	–4.0 A
	144 m Ω @ –2.5 V	
	200 m Ω @ –1.8 V	



P-CHANNEL MOSFET

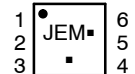
P-CHANNEL MOSFET



Pin 1

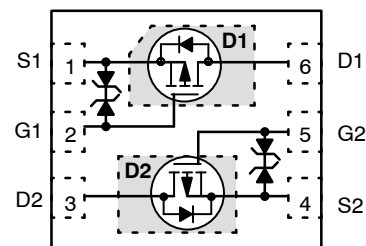
WDFN6
CASE 506AN

MARKING DIAGRAM



JE = Specific Device Code
M = Date Code
▪ = Pb–Free Package
(Note: Microdot may be in either location)

PIN CONNECTIONS



(Top View)

ORDERING INFORMATION

Device	Package	Shipping†
NTLJD3181PZTAG	WDFN6 (Pb–Free)	3000/Tape & Reel
NTLJD3181PZTBG	WDFN6 (Pb–Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NTLJD3181PZ

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
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SINGLE OPERATION (SELF-HEATED)

Junction-to-Ambient – Steady State (Note 3)	$R_{\theta JA}$	83	°C/W
Junction-to-Ambient – Steady State Min Pad (Note 4)	$R_{\theta JA}$	177	
Junction-to-Ambient – $t \leq 5$ s (Note 3)	$R_{\theta JA}$	54	

DUAL OPERATION (EQUALLY HEATED)

Junction-to-Ambient – Steady State (Note 3)	$R_{\theta JA}$	58	°C/W
Junction-to-Ambient – Steady State Min Pad (Note 4)	$R_{\theta JA}$	133	
Junction-to-Ambient – $t \leq 5$ s (Note 3)	$R_{\theta JA}$	40	

3. Surface Mounted on FR4 Board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).
4. Surface Mounted on FR4 Board using the minimum recommended pad size (30 mm², 2 oz Cu).

NTLJD3181PZ

MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	-20			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	$I_D = -250\text{ }\mu\text{A}$, Ref to 25°C		13		mV/ $^\circ\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -16\text{ V}, V_{GS} = 0\text{ V}$	$T_J = 25^\circ\text{C}$		-1.0	μA
			$T_J = 85^\circ\text{C}$		-10	
Gate-to-Source Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 8.0\text{ V}$			± 10	μA

ON CHARACTERISTICS (Note 5)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\text{ }\mu\text{A}$	-0.4		-1.0	V
Gate Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$			2.0		mV/ $^\circ\text{C}$
Drain-to-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = -4.5\text{ V}, I_D = -2.0\text{ A}$		68	100	m Ω
		$V_{GS} = -2.5\text{ V}, I_D = -2.0\text{ A}$		90	144	
		$V_{GS} = -1.8\text{ V}, I_D = -1.7\text{ A}$		125	200	
Forward Transconductance	g_{FS}	$V_{DS} = -5.0\text{ V}, I_D = -2.0\text{ A}$		6.5		S

CHARGES, CAPACITANCES AND GATE RESISTANCE

Input Capacitance	C_{ISS}	$V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}, V_{DS} = -10\text{ V}$		450		pF
Output Capacitance	C_{OSS}			90		
Reverse Transfer Capacitance	C_{RSS}			62		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -4.5\text{ V}, V_{DS} = -10\text{ V}, I_D = -3.8\text{ A}$		5.2	7.8	nC
Threshold Gate Charge	$Q_{G(TH)}$			0.3		
Gate-to-Source Charge	Q_{GS}			0.84		
Gate-to-Drain Charge	Q_{GD}			1.5		

SWITCHING CHARACTERISTICS (Note 6)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -4.5\text{ V}, V_{DD} = -5.0\text{ V}, I_D = -2.0\text{ A}, R_G = 2.0\text{ }\Omega$		6.6		ns
Rise Time	t_r			9.0		
Turn-Off Delay Time	$t_{d(OFF)}$			14		
Fall Time	t_f			12.5		

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Recovery Voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_S = -1.0\text{ A}$	$T_J = 25^\circ\text{C}$		-0.73	-1.0	V
			$T_J = 125^\circ\text{C}$		-0.62		
Reverse Recovery Time	t_{RR}	$V_{GS} = 0\text{ V}, dI_{SD}/dt = 100\text{ A}/\mu\text{s}, I_S = -1.0\text{ A}$		23		ns	
Charge Time	t_a			13			
Discharge Time	t_b			10			
Reverse Recovery Time	Q_{RR}			10		nC	

5. Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2\%$.

6. Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES ($T_J = 25^\circ\text{C}$ unless otherwise noted)

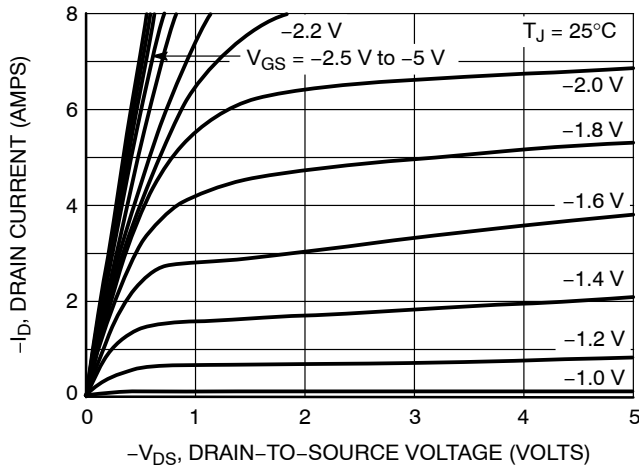


Figure 1. On-Region Characteristics

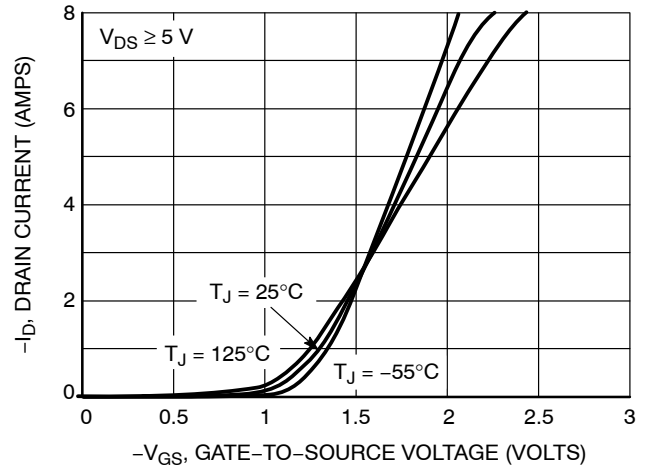


Figure 2. Transfer Characteristics

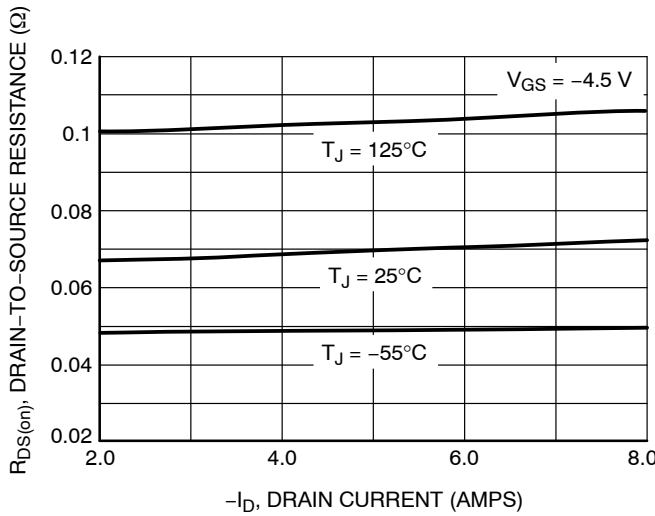


Figure 3. On-Resistance versus Drain Current

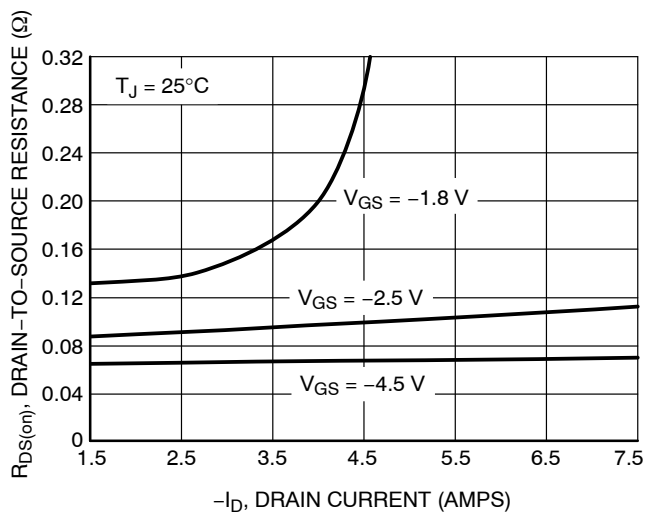


Figure 4. On-Resistance versus Drain Current and Gate Voltage

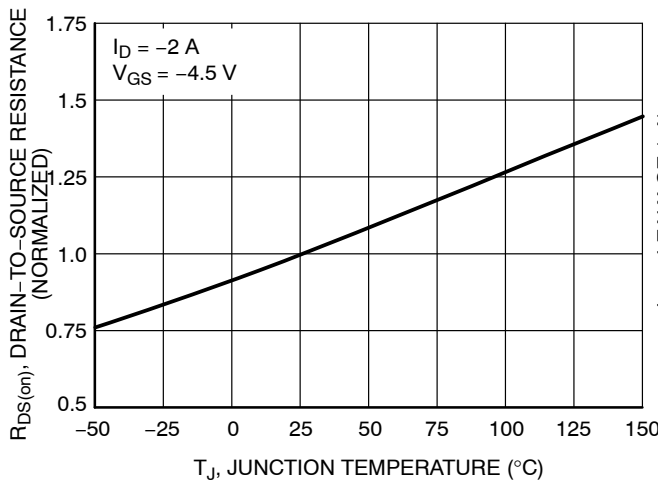


Figure 5. On-Resistance Variation with Temperature

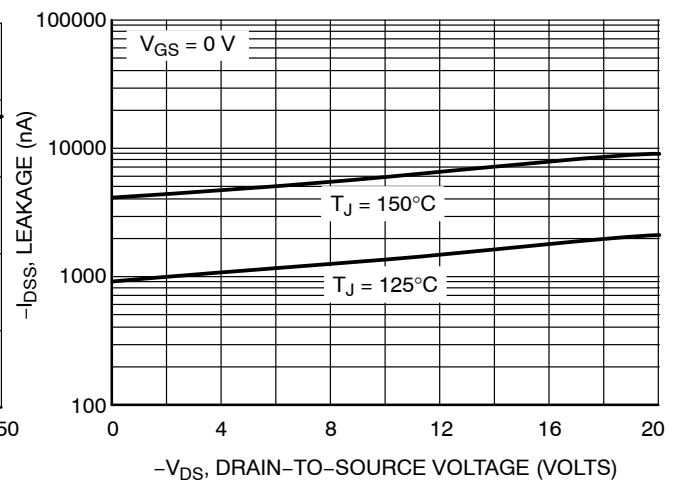


Figure 6. Drain-to-Source Leakage Current versus Voltage

TYPICAL PERFORMANCE CURVES ($T_J = 25^\circ\text{C}$ unless otherwise noted)

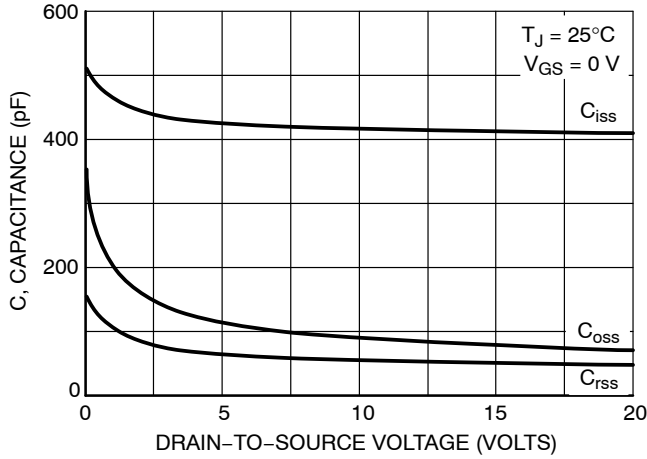


Figure 7. Capacitance Variation

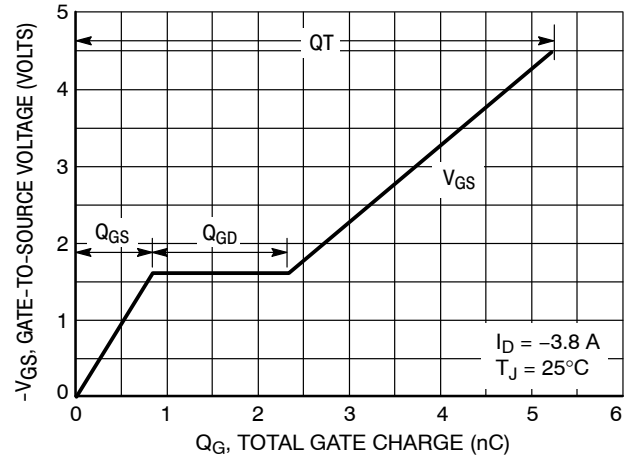


Figure 8. Gate-To-Source and Drain-To-Source Voltage versus Total Charge

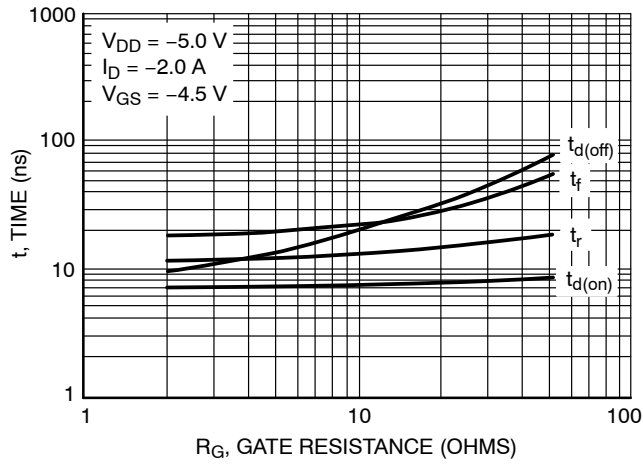


Figure 9. Resistive Switching Time Variation versus Gate Resistance

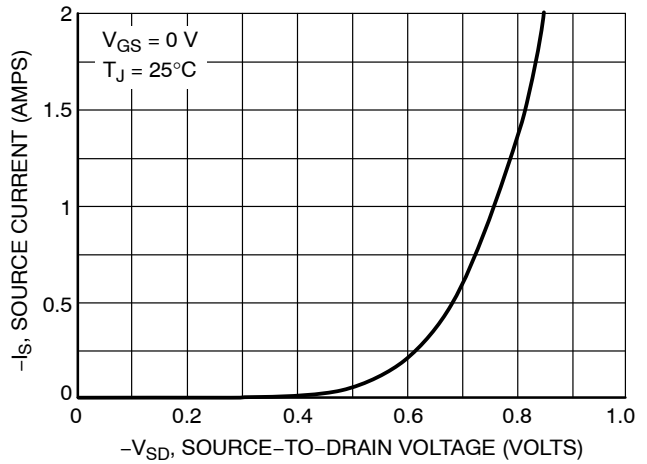


Figure 10. Diode Forward Voltage versus Current

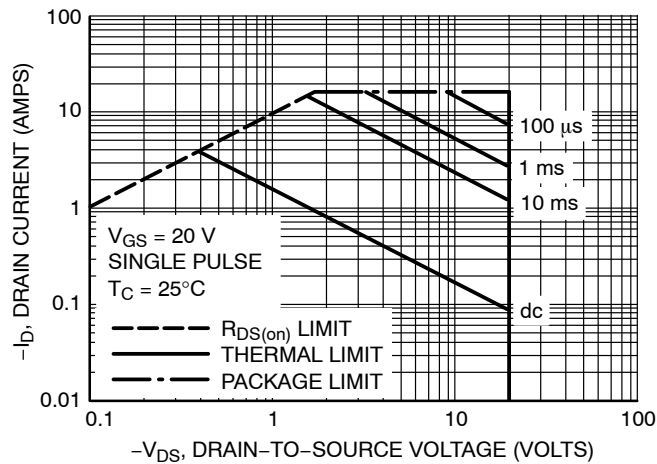


Figure 11. Maximum Rated Forward Biased Safe Operating Area

NTLJD3181PZ

TYPICAL PERFORMANCE CURVES ($T_J = 25^\circ\text{C}$ unless otherwise noted)

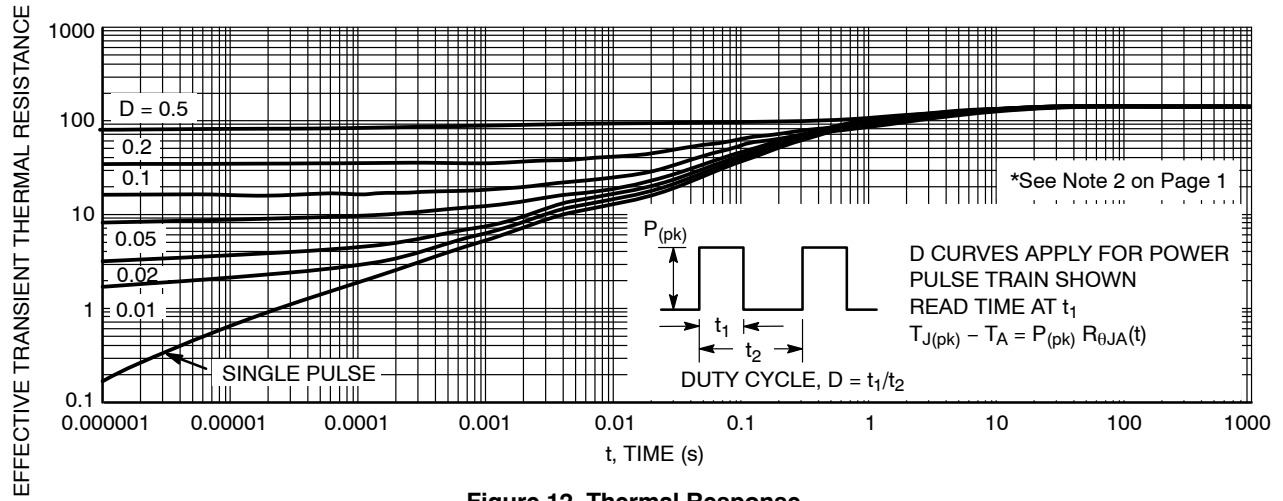
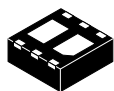


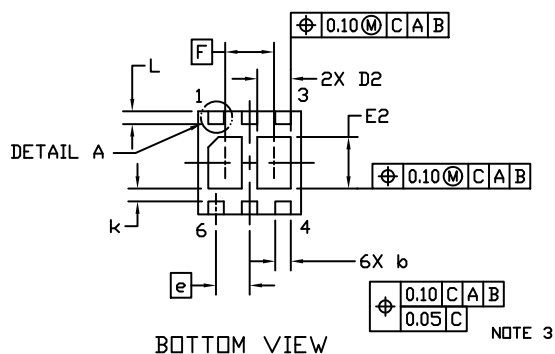
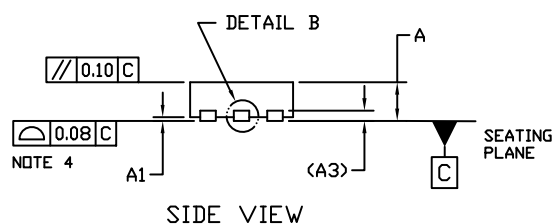
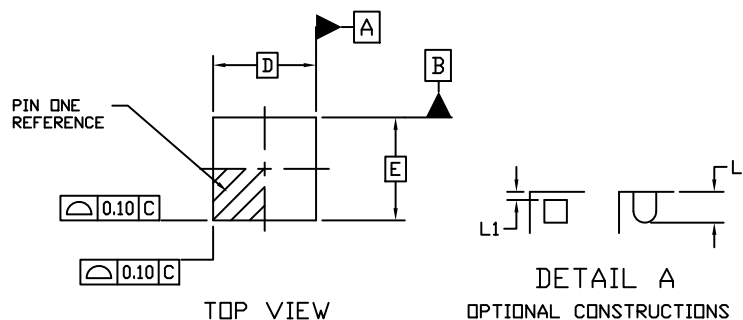
Figure 12. Thermal Response

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



WDFN6 2x2, 0.65P
CASE 506AN
ISSUE H

DATE 25 JAN 2022



GENERIC MARKING DIAGRAM*



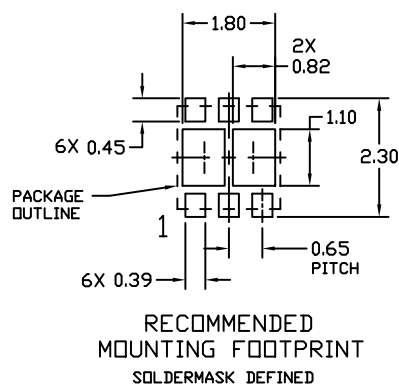
XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN.	MAX.
A	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.25	0.35
D	2.00 BSC	
D2	0.57	0.77
E	2.00 BSC	
E2	0.90	1.10
e	0.65 BSC	
F	0.95 BSC	
k	0.25 REF	
L	0.20	0.30
L1	---	0.10



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